Single 2-Input NOR Gate with Open Drain Output

The MC74VHC1G03 is an advanced high speed CMOS 2-input NOR gate with an open drain output fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including an open drain output which provides the capability to set output switching level. This allows the MC74VHC1G03 to be used to interface 5 V circuits to circuits of any voltage between V_{CC} and 7 V using an external resistor and power supply.

The MC74VHC1G03 input structure provides protection when voltages up to 7 V are applied, regardless of the supply voltage.

- High Speed: $t_{PD} = 3.6 \text{ ns}$ (Typ) at $V_{CC} = 5 \text{ V}$
- Low Internal Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on Inputs
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 62

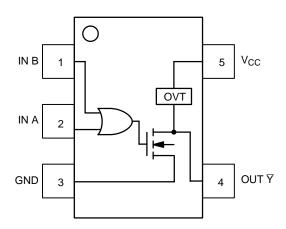


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



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SC70-5/SC-88A/SOT-353 DF SUFFIX CASE 419A



MARKING

Pin 1



SOT23-5/TSOP-5/SC59-5 DT SUFFIX CASE 483



d = Date Code

PIN ASSIGNMENT						
1	IN B					
2	IN A					
3	GND					
4	OUT ₹					
5	V _{CC}					

FUNCTION TABLE

Inp	uts	Output
Α	В	Y
L	L	Z
L	Н	L
Н	L	L
Н	Н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Characte	ristics	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage	$V_{CC} = 0$ High or Low State	-0.5 to 7.0 -0.5 to V _{CC} + 0.5	V
I _{IK}	Input Diode Current		-20	mA
I _{OK}	Output Diode Current	V _{OUT} < GND; V _{OUT} > V _{CC}	+20	mA
I _{OUT}	DC Output Current, per Pin		+25	mA
I _{CC}	DC Supply Current, V _{CC} and GND		+50	mA
P _D	Power Dissipation in Still Air at 85°C	SC70-5/SC-88A TSOP-5	150 200	mW
θ_{JA}	Thermal Resistance	SC70-5/SC-88A (Note 1) TSOP-5	350 230	°C/W
T _L	Lead Temperature, 1 mm from Case for	10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
T _{STG}	Storage Temperature Range		-65 to +150	°C
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I _{LATCH-UP}	Latch-Up Performance Above V	CC and Below GND at 125°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit	
V _{CC}	DC Supply Voltage	2.0	5.5	V	
V _{IN}	DC Input Voltage	0.0	5.5	V	
V _{OUT}	DC Output Voltage	0.0	7.0	V	
T _A	Operating Temperature Range		- 55	+125	°C
t _r , t _f	Input Rise and Fall Time	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0	100 20	ns/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

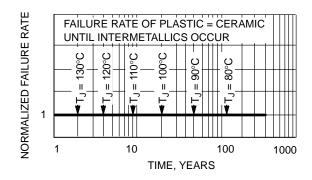


Figure 3. Failure Rate vs. Time Junction Temperature

DC ELECTRICAL CHARACTERISTICS

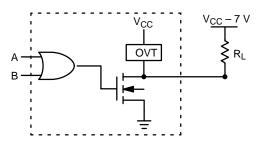
			V _{CC}	1	T _A = 25°C		T _A ≤	85°C	-55 ≤ T _A	≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Minimum High–Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V _{IL}	Maximum Low–Level Input Voltage		2.0 3.0 4.5 5.5			0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65		0.5 0.9 1.35 1.65	V
V _{OL}	Maximum Low-Level Output Voltage V _{IN} = V _{IH} or V _{IL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \mu\text{A}$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	V
I _{IN}	Maximum Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1.0		20		40	μΑ
I _{OPD}	Maximum Off-state Leakage Current	V _{OUT} = 5.5 V	0			0.25		2.5		5.0	μΑ

AC ELECTRICAL CHARACTERISTICS Input $t_{\text{r}} = t_{\text{f}} = 3.0 \text{ ns}$

			1	T _A = 25°C		$T_A \le 85^{\circ}C$		$-55 \le T_A \le 125$ °C		
Symbol	Parameter	Test Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
Input A or B to Y		$V_{CC} = 3.3 \pm 0.3 \text{ V C}_{L} = 15 \text{ pF}$ $R_{L} = R_{I} = 500 \Omega$ $C_{L} = 50 \text{ pF}$		5.6 8.1	7.9 11.4		9.5 13.0		11.0 15.5	ns
		$V_{CC} = 5.0 \pm 0.5 \text{ V } C_L = 15 \text{ pF} $ $R_L = R_I = 500 \Omega$ $C_L = 50 \text{ pF}$		3.6 5.1	5.5 7.5		6.5 8.5		8.0 10.0	
t _{PLZ}	Maximum Output Disable Time	$V_{CC} = 3.3 \pm 0.3 \text{ V C}_{L} = 50 \text{ pF}$ $R_{L} = R_{I} = 500 \Omega$		8.1	11.4		13.0		15.5	ns
		$V_{CC} = 5.0 \pm 0.5 \text{ V C}_{L} = 50 \text{ pF}$ $R_{L} = R_{I} = 500 \Omega$		5.1	7.5		8.5		10.0	
C _{IN}	Maximum Input Capacitance			4	10		10		10	pF

		Typical @ 25°C, V _{CC} = 5.0V	
C _{PD}	Power Dissipation Capacitance (Note 6)	18	pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.



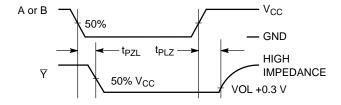
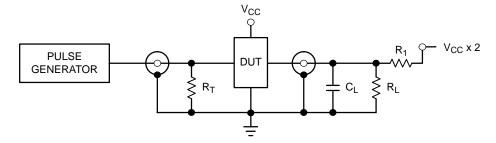


Figure 4. Output Voltage Mismatch Application

Figure 5. Switching Waveforms

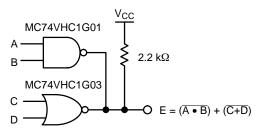


C_L = 50 pF equivalent (Includes jig and probe capacitance)

 $R_L = R_1 = 500 \Omega$ or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 6. Test Circuit





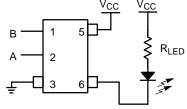


Figure 8. LED Driver

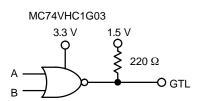


Figure 9. GTL Driver

DEVICE ORDERING INFORMATION

	Device Nomenclature								
Device Order Number	Logic Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type (Name/SOT#/ Common Name)	Tape and Reel Size	
MC74VHC1G03DFT1	MC	74	VHC1G	03	DF	T1	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit	
MC74VHC1G03DFT2	MC	74	VHC1G	03	DF	T2	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit	
MC74VHC1G03DTT1	MC	74	VHC1G	03	DT	T1	SOT23-5/TSOP-5/ SC59-5	178 mm (7 in) 3000 Unit	

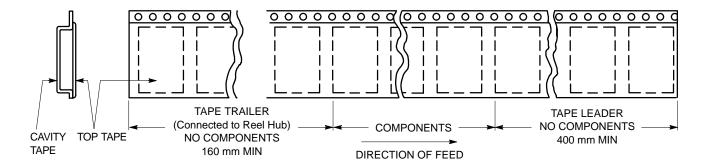


Figure 10. Tape Ends for Finished Goods

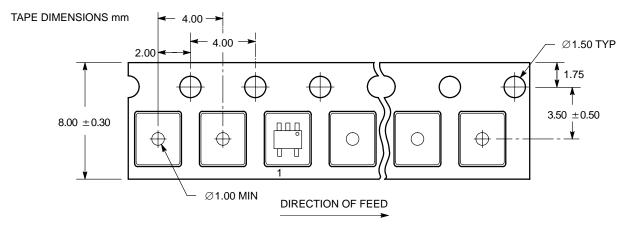


Figure 11. SC-70-5/SC-88A/SOT-353 DFT1 Reel Configuration/Orientation

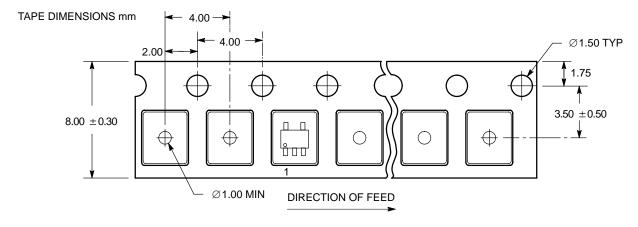


Figure 12. SC-70/SC-88A/SOT-353 DFT2 and SOT23-5/TSOP-5/SC59-5 DTT1 Reel Configuration/Orientation

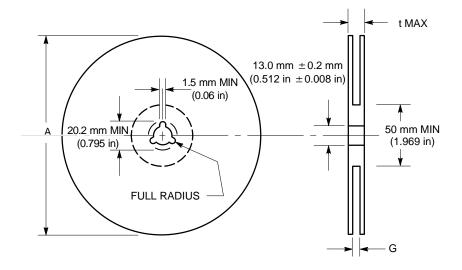


Figure 13. Reel Dimensions

REEL DIMENSIONS

Tape Size	T and R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7 in)	8.4 mm, + 1.5 mm, -0.0 (0.33 in + 0.059 in, -0.00)	14.4 mm (0.56 in)

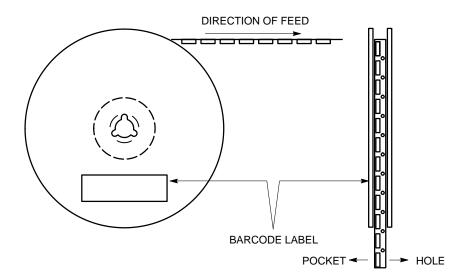
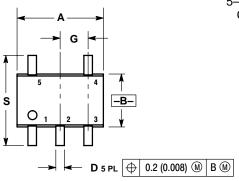


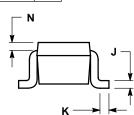
Figure 14. Reel Winding Direction

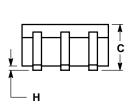
PACKAGE DIMENSIONS

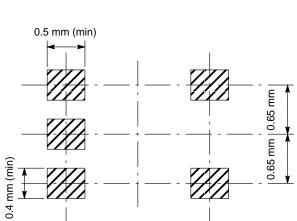
SC70-5/SC-88A/SOT-353 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-02 ISSUE F









1.9 mm

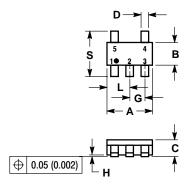
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

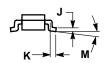
	INC	HES	MILLIM	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004	-	0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008 REF		0.20	REF	
S	0.079	0.087	2.00	2.20	

PACKAGE DIMENSIONS

SOT23-5/TSOP-5/SC59-5 **DT SUFFIX**

5-LEAD PACKAGE CASE 483-01 **ISSUE B**

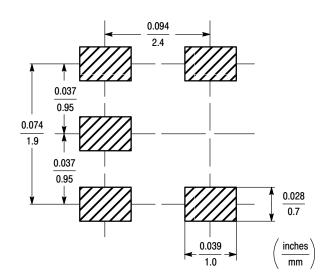




NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0 °	10°	0°	10°
S	2.50	3.00	0.0985	0.1181



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